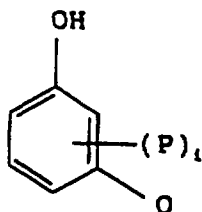


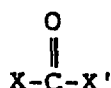
ABSTRACT OF THE DISCLOSURE:

NOVEL ARYL ESTER COMPOUND, ITS PRODUCTION PROCESS, EPOXY RESIN COMPOSITION USING SAID COMPOUND, AND COPPER-CLAD LAMINATE USING THE EPOXY RESIN COMPOSITION

An aryl ester compound composed of a polyhydric phenol in which at least one OH group has been esterified with an organic acid or its derivatives having 1 to 20 carbon atoms, said polyhydric phenol being the condensation product of a phenolic compound represented by the general formula:



with a carbonyl compound represented by the general formula:



which aryl ester compound can give, when used as a curing agent for an epoxy resin, a cured product having a low dielectric constant and a low dielectric loss tangent; an epoxy resin composition comprising as the essential components an epoxy resin, said aryl ester compound and a cure accelerator; and a copper-clad laminate using the epoxy resin composition. The copper-clad laminate has a low dielectric constant and a low dielectric loss tangent and is excellent in adhesiveness as compared with

- 2 -

conventional ones, and hence, is suitable for multilayer printed wiring board for high speed operation, especially at high-frequency region.